

# Welcome to O-leading

We are a professional PCB manufacturer with more than ten years of experience. Product range: single-sided, double-sided, multilayer PCB, flexible PCB and MCPCB. We can provide a rapid prototyping service: S / S in 24 hours, 4-8 units in 48-96 production hours.

MINIMUM COPPER PLATE HOLES .025 AVG, .020 MIN .. HOLES CAN NOT BE CONNECTED

Packaged with clear bubble colorless film, 25 pieces / bag, place the desiccant on the side, place the moisture indicator on top

CLICK HERE FOR MORE INFORMATION : [CERAMIC WAFER manufacturer china](#)

## Product description

PCB P / N	Q503701-A
Counting layers	2L
material	BASE ceramics
Board of directors	0.55 mm
copper thk	1/1 oz
Smallest hole size	1.6mm
Number of holes (pieces)	4
line w / s	/
Impedance check S / N (Tol%)	N
Surface finish	Electric silver
Silkscreen welding mask	green
Simple dimensions	Dim X (mm): 109; Dim Y (mm): 50
Panelisation	Dim X (mm): 109; Dim Y (mm): 50; UPS No: 1
Special: peelable mask	N
Routing / Punching	CNC



[www.o-leading.com](http://www.o-leading.com)

[Telecommunication PCB supplier china](#)

## FAQ

1. How does O-Leading guarantee quality?

Our high quality standard is obtained with the following.

1. The process is strictly controlled in accordance with ISO 9001: 2008 standards.
2. Extensive use of software in the management of the production process
3. cutting-edge test tools and tools. For example. Flying Probe, X-ray inspection, AOI (Automated Optical Inspector) and ICT (circuit test).
4. Quality assurance team specified with fault case analysis process
5. Staff training and continuous training

2. How does O-Leading maintain the competitive price?

In the last decade, the prices of many raw materials (for example, copper, chemicals) had doubled, tripled or quadrupled; The Chinese currency RMB appreciated 31% against the US dollar; And our labor costs also increased significantly. However, O-Leading has kept our prices constant. It's all about our innovations to reduce costs, avoid waste and improve efficiency. Our prices are very competitive in the industry with the same level of quality.

We believe in a partnership of mutual benefit with our customers. Our partnership will be mutually beneficial if we can offer you an advantage in terms of cost and quality.

3. What types of cards can the O-Leading process make?

FR4 common, high TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum / copper plates, PI,

etc.

4. What data are needed for PCB production?

It is better to provide data in the Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What is the typical process flow for multi-layer PCB?

Cut material → inner dry film → internal engraving → internal AOI → Multi-bond → overlapping pressing layers → Drilling → PTH → Plating → external dry film → Plating → external engraving → AOI → external welding mask → COD component → Finishing surface → Routing → E / T → Visual inspection.

## Our Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



# Certifications

CICC INSPECTION CERTIFICATION



**嘉泰认证**

**QUALITY MANAGEMENT SYSTEM CERTIFICATE**

Certificate No: 18118Q10347R05

**We hereby certify that**

**O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED**

Credit No: 61691591-000-07-18-7

Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VODEUS ROAD CENTRAL HK

Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards  
GB/T19001-2016 idt ISO9001:2015

**Scope of certification**  
Sales of printed circuit boards

Initial issuance period: February 27, 2018  
Renewal date: April 22, 2019  
This certificate is valid during: April 22, 2019 – February 26, 2021  
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
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The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the state. The effectiveness of this certificate shall be restricted to those activities which are covered by the certification. The actual information of this certification can be searched on the internet of CICC www.cicc.com.cn by the site of internet www.cicc.com.cn.






CICC INSPECTION CERTIFICATION



**嘉泰认证**

**质量管理体系认证证书**

证书号: 18118Q10347R05

**兹证明**

**诚领供应链(香港)有限公司**

统一社会信用代码: 61691591-000-07-18-7

注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室

经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

**建立的质量管理体系符合**  
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

**认证范围**  
印刷线路板的销售

初次获证日期: 2018年02月27日  
换证日期: 2019年04月22日  
证书有效期: 自2019年04月22日至2021年02月26日  
在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

第一次监督	第二次监督	黏贴处
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本证书认证范围不包括未取得有效的国家规定的行政许可、资质许可的产品/服务范围; 本证书通过CICC定期监督审核保持, 与年度《保持认证通知书》共同方为有效; 本证书信息可在国家认监委网站: www.cca.gov.cn及CICC网站www.cicc.com.cn查询。








Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-006089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



Member of the SGS Group (SGS SA)



Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

Table with columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected ( < MDL )
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with columns: Test Item(s), Limit, Unit, MDL, Q/T. Lists various metals and organohalogen compounds with their respective limits and detection methods.



Member of the SGS Group (SGS SA)



## ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

## Wiring, Printed - Component

See General Information for Wiring, Printed - Component

**O-LEADING SUPPLY CHAIN (HK) CO LTD**

E490354

ROOM 1205, 12/F  
TAI SANG BANK BLDG  
130-132 DES VOEUS ROAD  
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max	Max		Meets UL796	C		
	Min	Edge			Area Diam	Solder Limits	Oper Temp			Flame	
	mm(in)	mm(in)			mm(in)	C	sec	C	Class	DSR	I
<b>Multilayer (mass laminate) printed wiring boards.</b>											
<b>O-LEADING-401</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
<b>O-LEADING-407</b>	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
<b>Multilayer printed wiring boards.</b>											
<b>O-LEADING-408</b>	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
<b>Single layer printed wiring boards.</b>											
<b>O-LEADING-002</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
<b>O-LEADING-003</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
<b>O-LEADING-033</b>	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
<b>O-LEADING-205</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-206</b>	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-D01</b>	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
<b>O-LEADING-S01</b>	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

## WIRING, PRINTED - COMPONENT | UL Product iQ

<b>O-LEADING-S02</b>	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
<b>O-LEADING-S03</b>	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

\* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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# Packaging & Delivery

## Shipping service





Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

## Process Capability

### PCB Production Capabilities

Layer Count: 1Layer-32Layer

Finished copper thickness 1/3oz-12oz

Min Line width/spacing internal 3.0mil/3.0mil

Min Line width/spacing external: 4.0mil/4.0mil

Max Aspect Ratio: 10:1

Board thickness 0.2mm-5.0mm

Max Panel size(inches): 635\*1500mm

Minimum Drilled Hole Size: 4mil

Plated Hole Tolerance: +/-3mil

Blind/Buried Vias (All Types): YES

Via Fill(Conductive,Non-Conductive): YES

Base Material: FR-4,FR-4high Tg,Halogen free material,Rogers,Aluminium base,Polyimide,

Heavy Copper

Surface finishes: HASL,OSP,ENIG,HAL-LF,Immersion silver,Immersion Tin,Gold fingers,Carbon ink

### SMT Production Capabilities

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board  
Max PCB size: 510x460mm  
Min PCB size□50x50mm  
PCB Thickness□0.5mm-4.5mm  
Board thickness□0.5-4mm  
Min Components size: 0201  
Standard chip size component: 0603 and larger  
Component max height□15mm  
Min lead pitch: 0.3mm  
Min BGA ball pitch:0.4mm  
Placement precision: +/-0.03mm